Yu-An Shen

List of Publications by Year
in descending order

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38
papers

510
citations

623188
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676716
22
g-index

40
all docs

40
docs citations

40
times ranked

202
citing authors

#	Article	IF	Citations
1	Graphene as a diffusion barrier at the interface of Liquidâ€“State low-melting Snâ€“58Bi alloy and copper foil. Applied Surface Science, 2022, 578, 152108.	3.1	18
2	Nanotwin orientation on history-dependent stress decay in Cu nanopillar under constant strain. Nanotechnology, 2022, 33, 155708.	1.3	6
3	Effect of Cu on the interfacial reaction between Sn-based solders and FeCoNiCu alloys. Intermetallics, 2022, 144, 107530.	1.8	9
4	Microstructure Evolution and Shear Strength of Tin-Indium-xCu/Cu Joints. Metals, 2022, 12, 33.	1.0	7
5	Contact Angle Analysis and Intermetallic Compounds Formation Between Solders and Substrates under Formic acid Atmosphere. Journal of Advanced Joining Processes, 2022, , 100118.	1.5	1
6	A Study on Strengthening Mechanisms in Sn-0.7Cu via Microstructural Observation, Elemental Distribution, and Grain-Size Analysis. , 2022, , .		1
7	Electromigration behavior of silver thin film fabricated by electron-beam physical vapor deposition. Journal of Materials Science, 2021, 56, 9769-9779.	1.7	6
8	Effect of Cu addition on the microstructure and mechanical properties of Inâ€“Sn-based low-temperature alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 804, 140785.	2.6	11
9	Investigation of FeCoNiCu properties: Thermal stability, corrosion behavior, wettability with Sn-3.0Ag-0.5Cu and interlayer formation of multi-element intermetallic compound. Applied Surface Science, 2021, 546, 148931.	3.1	23
10	Effects of impurities on void formation at the interface between Sn-3.0Ag-0.5Cu and Cu electroplated films. Journal of Materials Science: Materials in Electronics, 2021, 32, 11944-11951.	1.1	4
11	Observation of void formation patterns in SnAg films undergoing electromigration and simulation using random walk methods. Scientific Reports, 2021, 11, 8668.	1.6	2
12	The voids growth path on Sn-Ag thin film under high current density. , 2021, , .		0
13	Extremely thin interlayer of multi-element intermetallic compound between Sn-based solders and FeCoNiMn high-entropy alloy. Applied Surface Science, 2021, 558, 149945.	3.1	21
14	Fabrication of NiO/ZrO2 nanocomposites using ball milling-pyrolysis method. Vacuum, 2021, 191, 110370.	1.6	8
15	Wettability, interfacial reactions, and impact strength of Snâ€“3.0Agâ€“0.5Cu solder/ENIG substrate used for fluxless soldering under formic acid atmosphere. Journal of Materials Science, 2020, 55, 3107-3117.	1.7	14
16	Anisotropic Grain Growth in (111) Nanotwinned Cu Films by DC Electrodeposition. Materials, 2020, 13, 134.	1.3	8
17	In-situ observation of fluxless soldering of Sn-3.0Ag-0.5Cu/Cu under a formic acid atmosphere. Materials Chemistry and Physics, 2020, 239, 122309.	2.0	17
18	Interfacial transformation of preoxidized Cu microparticles in a formic-acid atmosphere for pressureless Cuâ€“Cu bonding. Journal of Materials Science: Materials in Electronics, 2020, 31, 14635-14644.	1.1	15

#	Article	IF	Citations
19	Mechanical and microstructural enhancements of Ag microparticle-sintered joint by ultrasonic vibration. Journal of Materials Science: Materials in Electronics, 2020, 31, 21711-21722.	1.1	2
20	Microstructure and mechanical properties of the Inâ€"48Snâ€"xAg low-temperature alloy. Journal of Materials Science, 2020, 55, 10824-10832.	1.7	11
21	Electrodeposition of Twinned Cu with Strong Texture Effect on Voiding Propensity in Electroplated Cu Solder Joints. Journal of the Electrochemical Society, 2020, 167, 162516.	1.3	15
22	Suppressed Growth of (Fe, Cr, Co, Ni, Cu)Sn2 Intermetallic Compound at Interface between Sn-3.0Ag-0.5Cu Solder and FeCoNiCrCu0.5 Substrate during Solid-state Aging. Scientific Reports, 2019, 9, 10210.	1.6	12
23	A Cu-Cu Bonding Method Using Preoxidized Cu Microparticles under Formic Acid Atmosphere. , 2019, , .		5
24	Sn-3.0Ag-0.5Cu/Sn-58Bi composite solder joint assembled using a low-temperature reflow process for PoP technology. Materials and Design, 2019, 183, 108144.	3.3	47
25	Effect of Substrates on Fracture Mechanism and Process Optimization of Oxidationâ€"Reduction Bonding with Copper Microparticles. Journal of Electronic Materials, 2019, 48, 2263-2271.	1.0	22
26	Improved mechanical properties induced by In and In & Zn double additions to eutectic Sn58Bi alloy. Journal of Materials Science: Materials in Electronics, 2019, 30, 7423-7434.	1.1	16
27	Effect of FeCoNiCrCu0.5 High-entropy-alloy Substrate on Sn Grain Size in Sn-3.0Ag-0.5Cu Solder. Scientific Reports, 2019, 9, 3658.	1.6	10
28	The newly developed Snâ€"Biâ€"Zn alloy with a low melting point, improved ductility, and high ultimate tensile strength. Materialia, 2019, 6, 100300.	1.3	35
29	Preferred orientation of Bi and effect of Sn-Bi microstructure on mechanical and thermomechanical properties in eutectic Sn-Bi alloy. Materialia, 2019, 6, 100309.	1.3	13
30	Thermomigration induced microstructure and property changes in Sn-58Bi solders. Materials and Design, 2019, 166, 107619.	3.3	35
31	The study of Sn-45Bi-2.6Zn alloy before and after thermal aging. , 2019, , .		0
32	Microstructure and Property Changes in Cu/Sn-58Bi/Cu Solder Joints During Thermomigration. , 2019, , .		3
33	Novel polarity effect on intermetallic compound thickness changes during electromigration in Cu/Sn-3.0Ag-0.5Cu/Cu solder joints. Journal of Applied Physics, 2019, 126, .	1.1	15
34	Effects of In and Zn Double Addition on Eutectic Sn-58Bi Alloy. , 2019, , .		2
35	Effect of Sn grain orientation on growth of Cu-Sn intermetallic compounds during thermomigration in Cu-Sn2.3Ag-Ni microbumps. Materials Letters, 2019, 236, 190-193.	1.3	26
36	Effect of Sn grain orientation on formation of Cu6Sn5 intermetallic compounds during electromigration. Scripta Materialia, 2017, 128, 6-9.	2.6	69

#	Article	IF	Citations
37	Effect of Sn grain orientation on the formation of Cu₆S₅ intermetallic compounds during electromigration. , 2016, , .		0
38	Study of grain size and orientation of 30 Âµm solder microbumps bonded by thermal compression. , 2015, , .		0